



Innovating in the MEMS Foundry Business
February 12, 2025

Dr. Kara Zappitelli & Scott Smyser

The MEMS foundry business needs innovation.

EXPENSIVE

INEFFICIENT

SLOW

CONVOLUTED

OUTDATED

The MEMS foundry business needs innovation.

**LONGER
TIME TO
MARKET**

EXPENSIVE
INEFFICIENT
SLOW
CONVOLUTED
OUTDATED

Science Foundry addresses these pain points

OUTDATED

EXPENSIVE

SLOW

INEFFICIENT

CONVOLUTED

- Rapid prototyping with MEMS multi-project wafers
- Streamlined operations with a custom MES
- Scaling up capacity quickly and efficiently

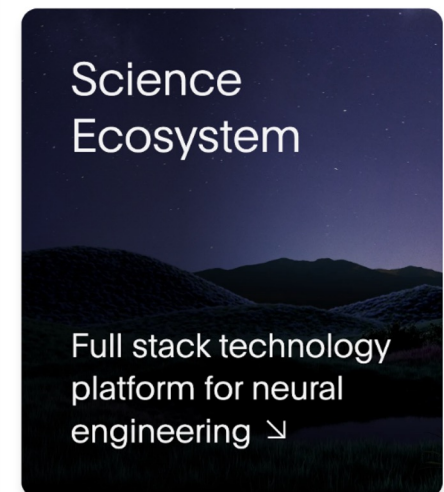
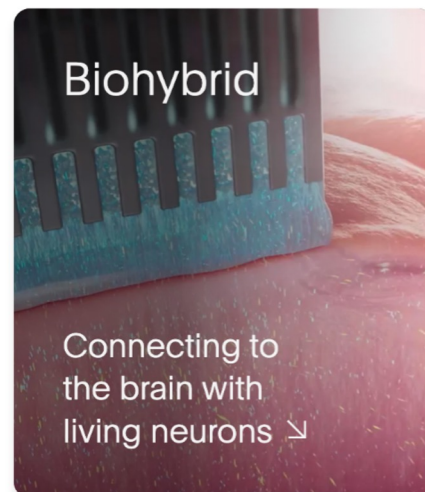
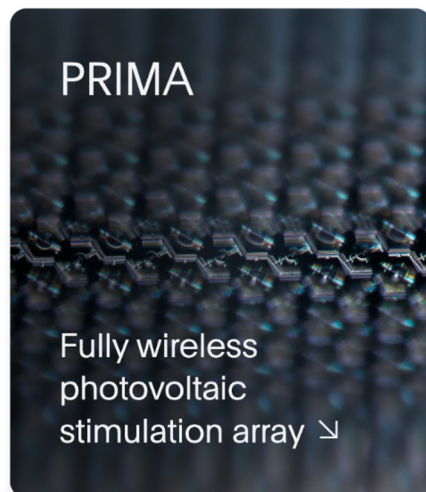
Science Corp Overview

- Founded April 2021
- Science Corporation is a clinical-stage medical technology company
 - Dozens of patients in six countries.
 - We work to restore quality of life to those with debilitating conditions for which there are no treatment options
- Headquartered in Alameda, California, we are a global company with secondary offices in Durham, North Carolina and Paris, France.



Science A brighter tomorrow enabled by neural engineering

We are a clinical stage, vertically integrated technology company focused on solving some of neuroscience's hardest questions and most serious unmet medical needs.



Two Broad Mandates

Restore Functionality

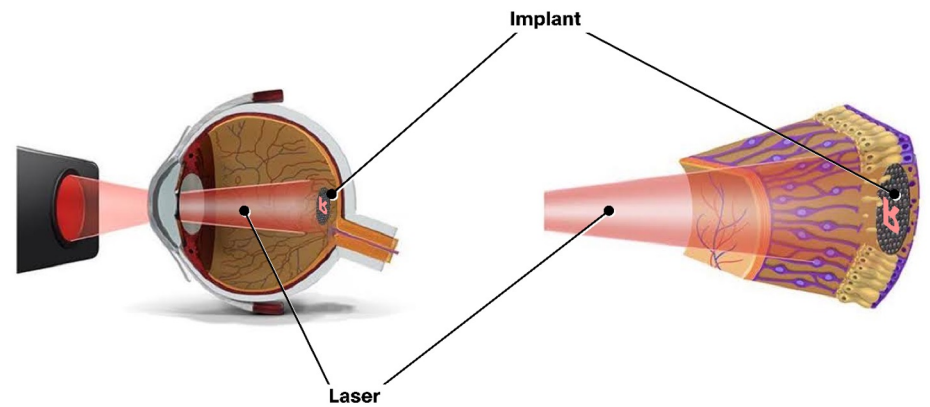
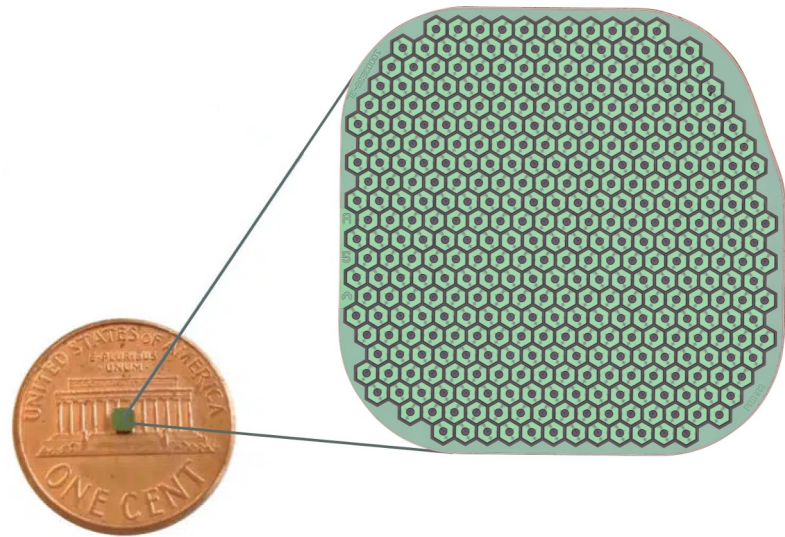
- Vision
- Cognition
- Mobility

Advance Neural Engineering

- Commercial Neural Interfaces

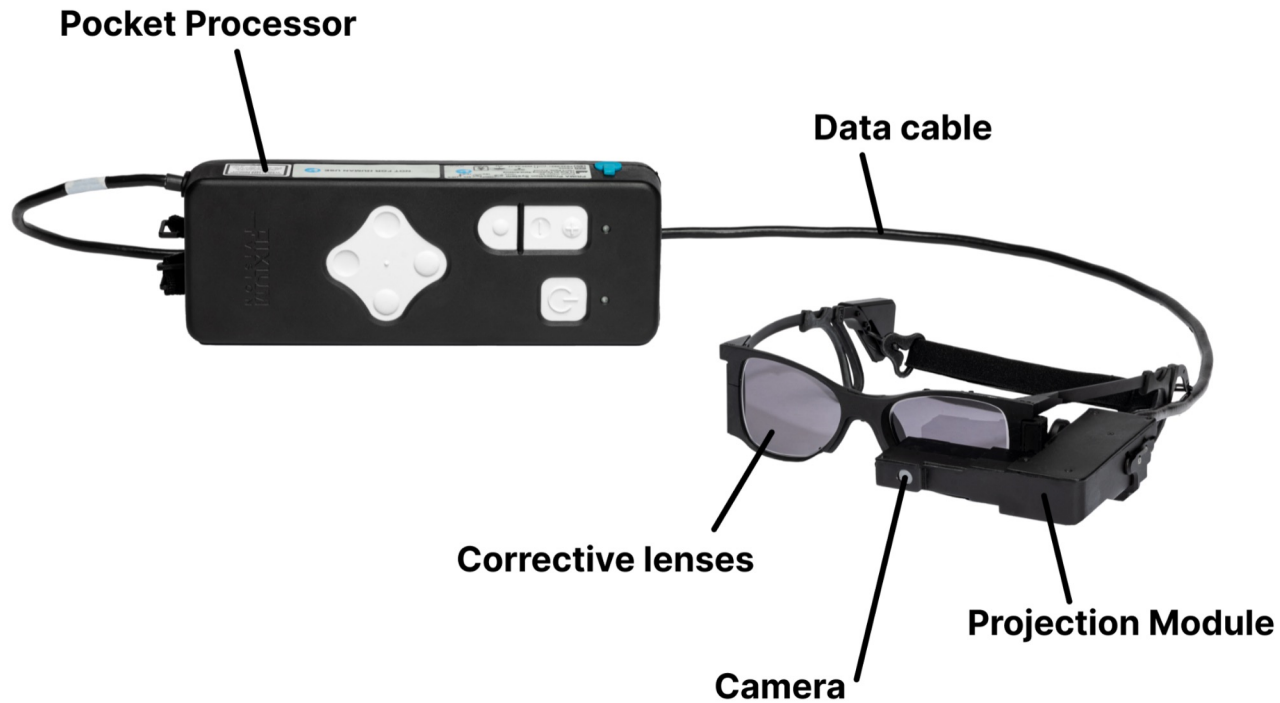
Restore Vision: PRIMA Implant

Photovoltaic device



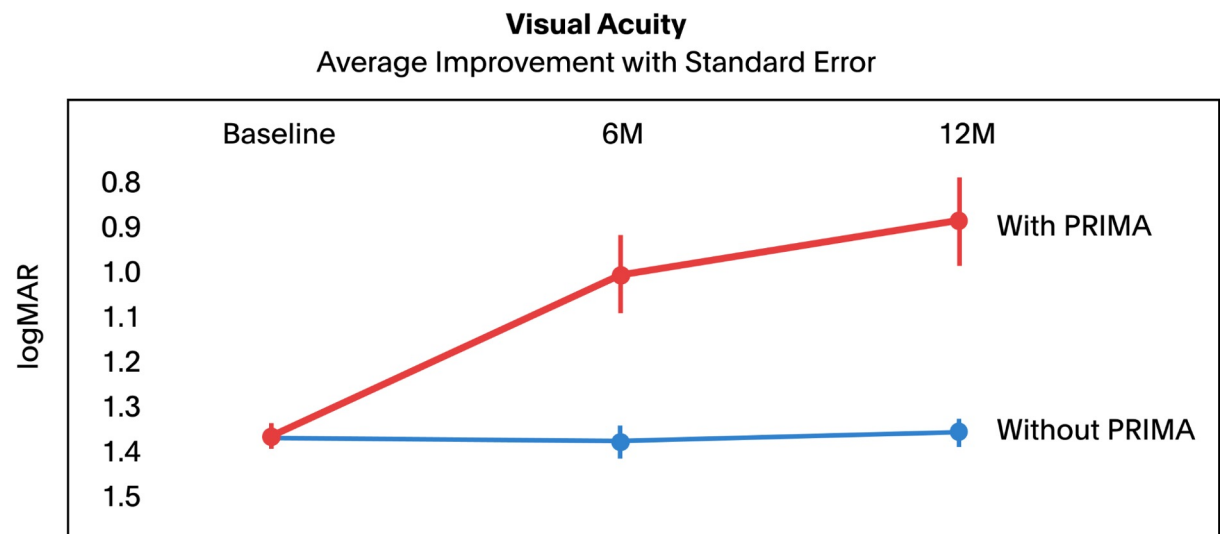
Restore Vision: PRIMA Implant

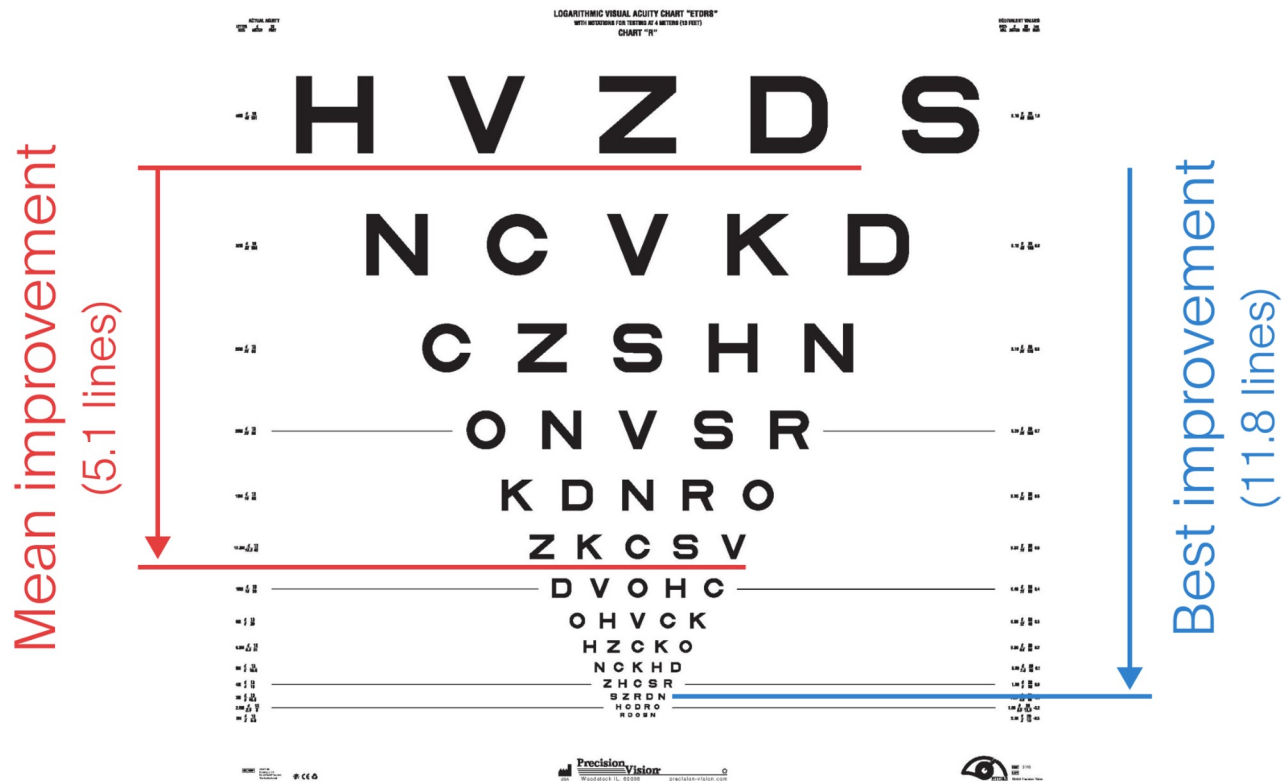
Companion



Preliminary Clinical Trial Results

- 38 Patients
- 17 sites across 5 countries
- Over age 60, with Geographic Atrophy > 4.5mm²
- logMAR 1.2 (20/320) or worse

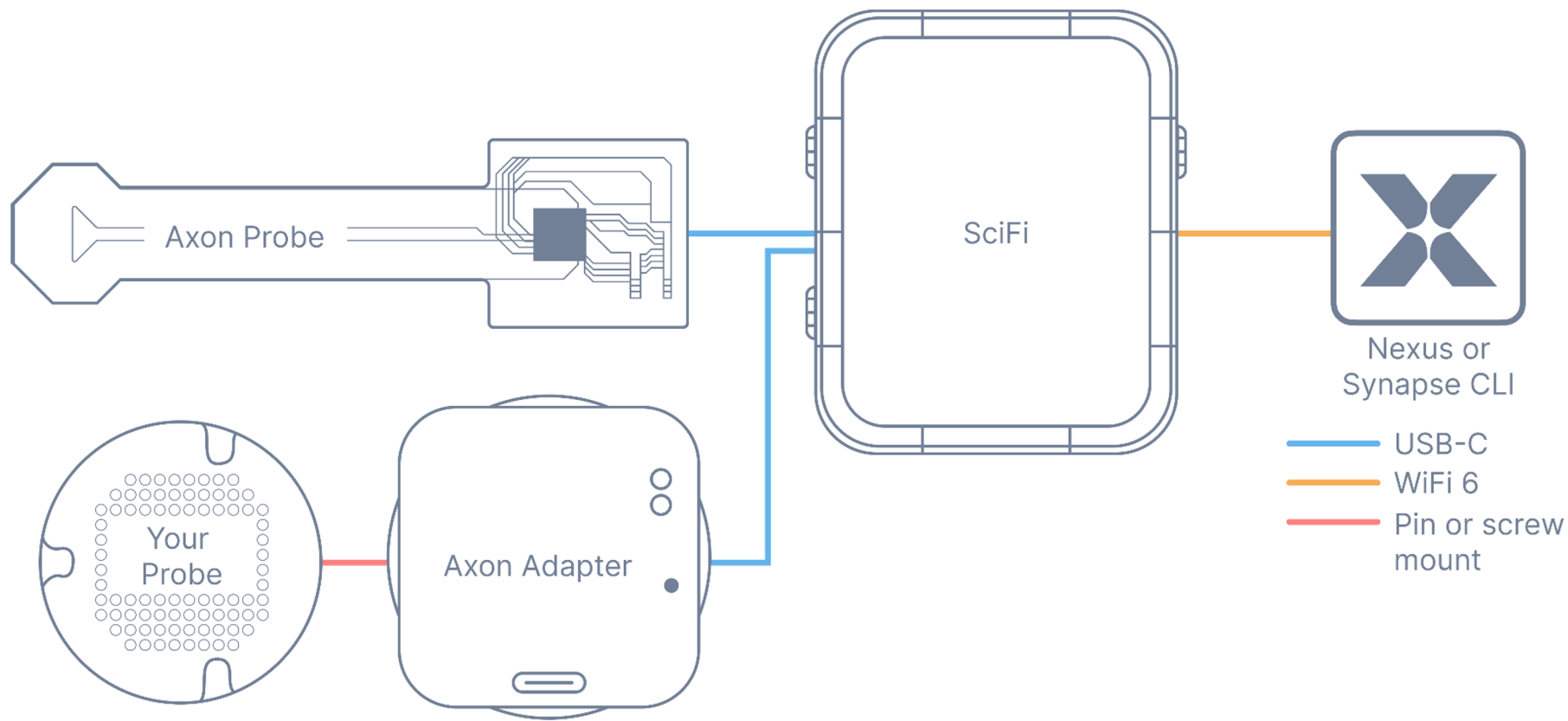




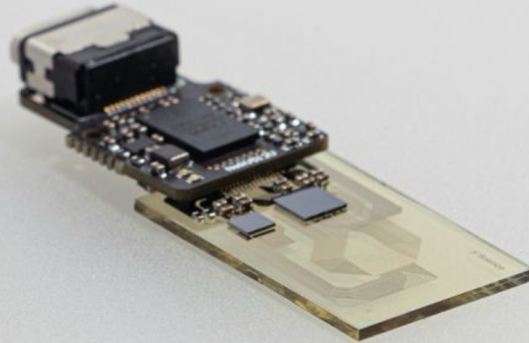
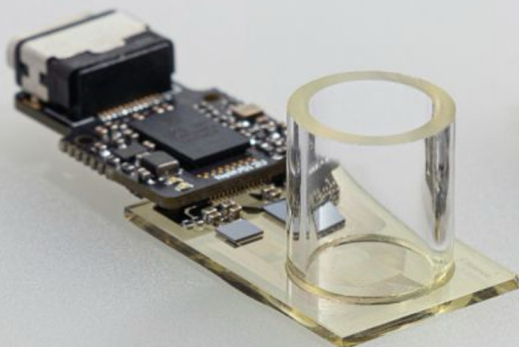
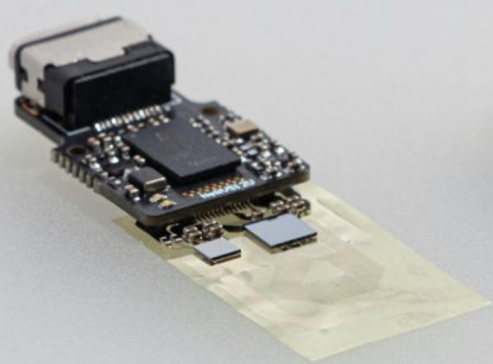
Includes use of digital zoom



Commercial Neural Interfaces



- USB-C
- WiFi 6
- Pin or screw mount



Ambitious mandates drive need for vertical integration at Science

- Need a lot of things fast
- Want to control our own destiny
- Lower barriers for others in our field
- Further neural engineering as a whole

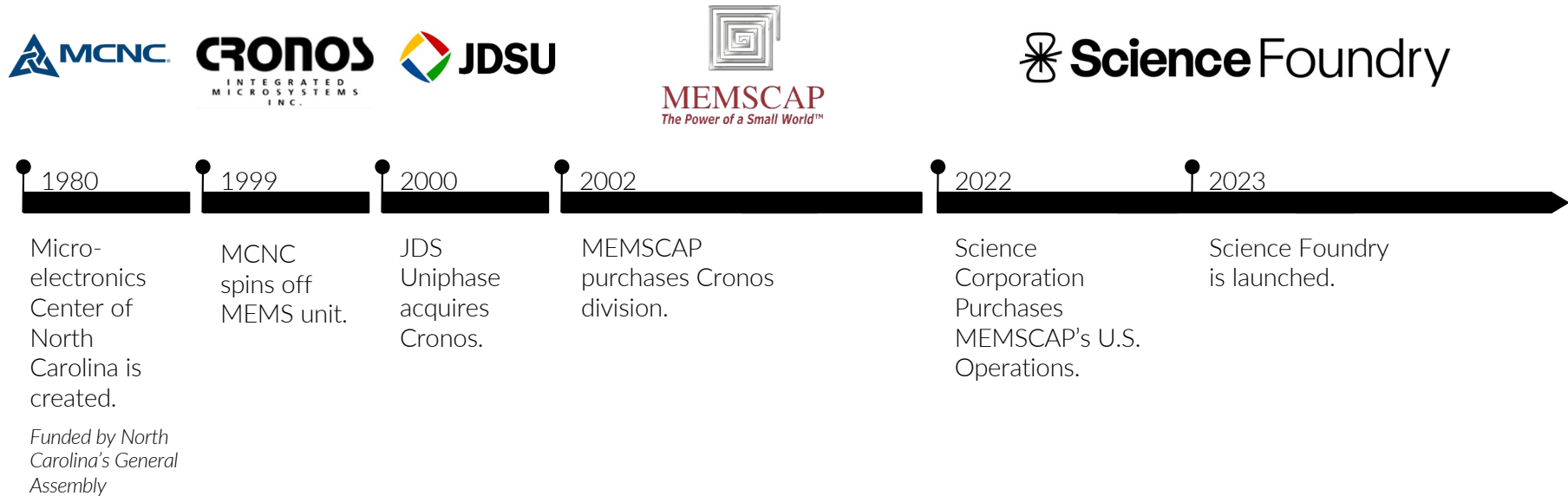
Ambitious mandates drive need for vertical integration at Science

- Need to get things fast
- Want to control the supply chain
- Lower barriers to entry
- Further integration

**WE BOUGHT
A FOUNDRY!**

Science Foundry Overview

New brand for an established fab

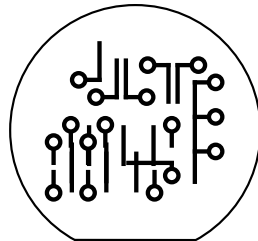


Science Foundry

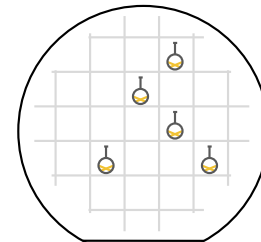
Build on Science's advanced MEMS capabilities for your own research or product development

5000 ft² of Class 100 Cleanroom • ISO 9001:2015 Certified • 6" Wafer Line • Durham, NC

Custom Processes




Multi-Project Wafer Runs




Science
Foundry is your
fastest path
from design to
device

 Dry Etching


Reactive ion
etching
Deep silicon
etching
Plasma cleaning

 Wet Etching

Wet metal
Wet oxide
Silicon etching
Immersion
cleaning

 Metallization

Evaporation
Au, Cu, Ti, Cr, Pt, Ni, Al
Sputtering
Cr, Au, Ti, TiW, Cu

 Lithography

Contact
lithography
Projection
lithography
Backside
alignment

 LPCVD

Oxide
Nitride
Polysilicon
Polysilicate glass

 Polymers


Polyimide
insulation
Polyimide
protection

 Dicing


Silicon
Glass
Quartz
Sapphire

 Post Processing

HF liquid release
HF vapor release
Critical CO
drying

 Wafer Bonding

Fusion
Glass-glass
Silicon-glass
Eutectic
Anodic

 Material Removal

Wafer polishing
Wafer grinding

 Metrology

SEM
Profilometry
Infrared inspection
Interferometry
Film analysis

We create a wide range of complex MEMS devices



Biomedical & Healthcare Technology

Neural Interface Devices
Microneedles
Microfluidic Chips
Ultrasound Devices



Industrial Sensing, Control & Automation

Inertial Sensors
Pressure Sensors
Gas Sensors
Environmental Sensors



Communications & Optoelectronics

Micro Mirrors
Imaging Devices
Optical Telecom Components
Silicon Photonics



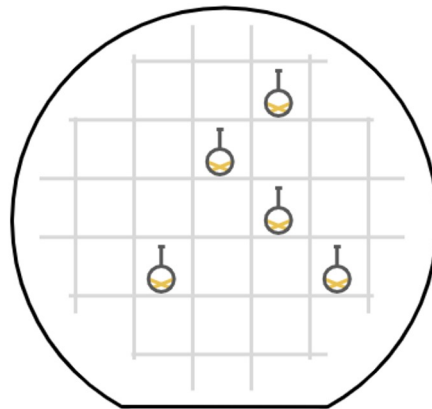
Advanced Computing & More

Quantum Computing
Internet of Things (IoT) Devices
Wearables Sensors
Your Novel MEMS Device

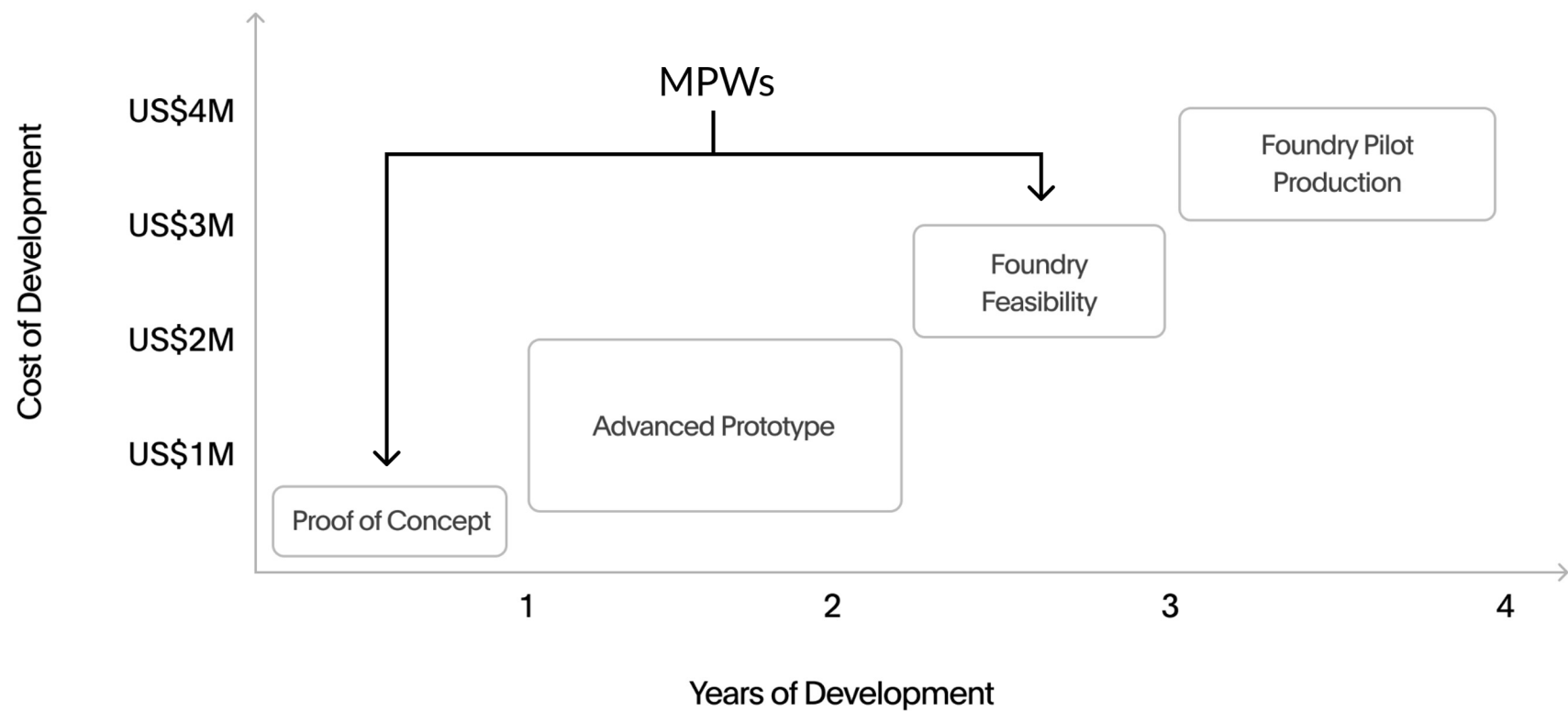
Science Foundry innovates in three key ways:

1. MEMS Multi-Project Wafer Offerings
2. Custom Manufacturing Execution System
3. Modular Facility Expansion

MEMS Multi-Project Wafers == Science Standard Technologies



The MEMS prototyping phase is LONG

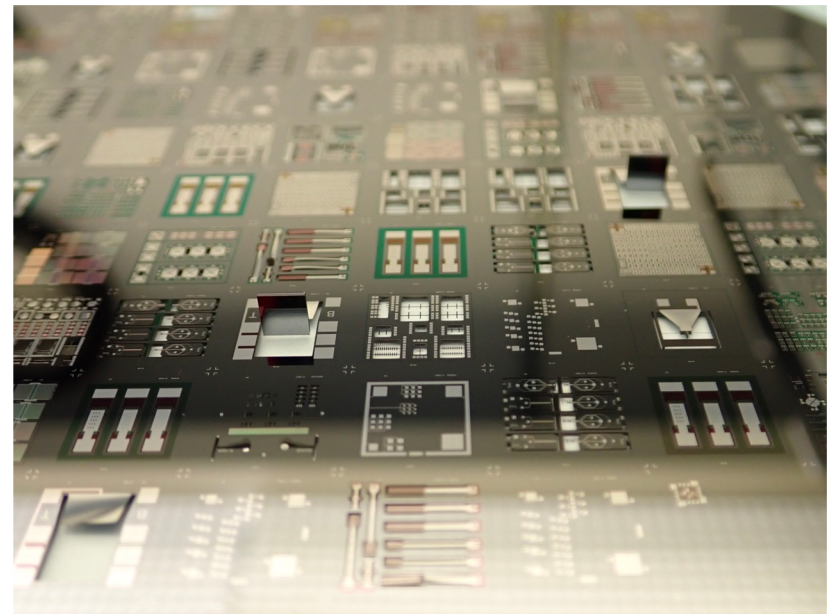


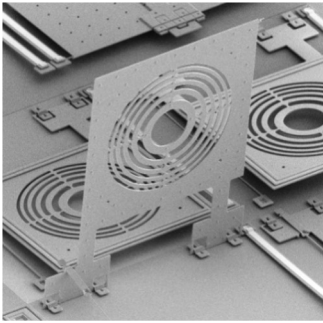
[adapted from MEMS Product Development, Fitzgerald et. al.]

MEMS Multi-Project Wafers (MPW)

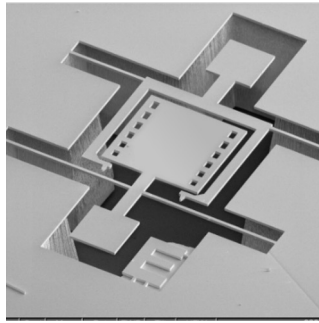
- Production quality processing
- User submitted designs
- Multiple scheduled runs/year
- 100,000s of devices shipped
- 200+ process runs

Fastest path from design to device!

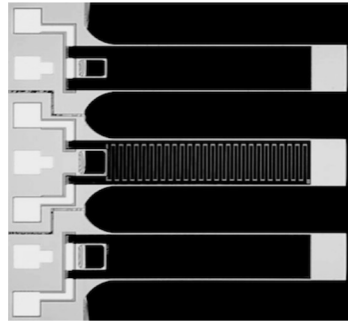




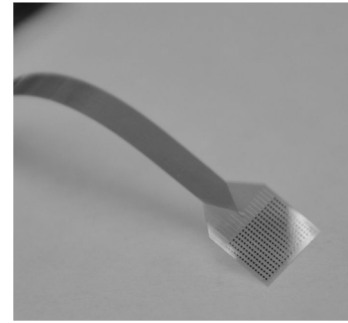
Poly



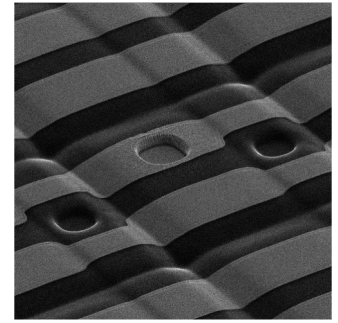
SOI



Piezo



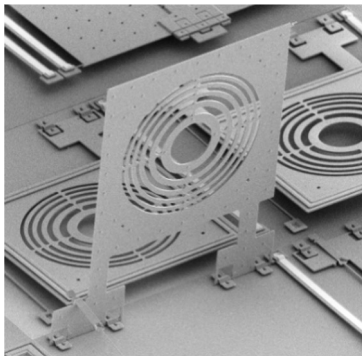
TFE



TFE+

Polysilicon

Once per year, ~18 week cycle time



Images courtesy of the School of Engineering Science at Simon Fraser University

Optical neural interfaces, biometric wearables, astronomy, laser communications, maskless lithography, and ultrasound wearables.

Nitride: 0.6 μm

Polysilicon 0: 0.5 μm

Oxide 1: 0.5 μm

Polysilicon 1: 2.0 μm

Oxide 2: 0.5 μm

Polysilicon 2: 1.5 μm

Metal: 0.5 μm

Substrate

- Eight masks
- Three polysilicon layers
- One metal layer

Silicon-on-Insulator (SOI)

3X per year, ~10 week cycle time

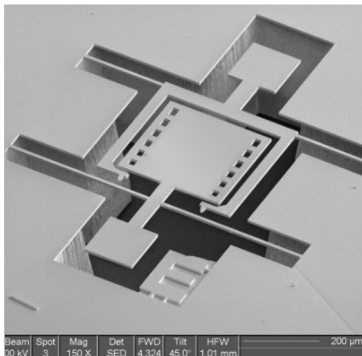


Image courtesy of the School of Engineering Science at Simon Fraser University

Optical fiber telecoms, automotive LiDAR, RF switches, nuclear energy, and electric grid monitoring

Pad metal: 0.52 μm

Silicon: 25 μm

Substrate: 400 μm

Buried oxide: 2 μm

Blanket metal: 0.65 μm

- Four masks
- SOI wafer
- Two metal layers

Piezo

3X per year, ~14 week cycle time

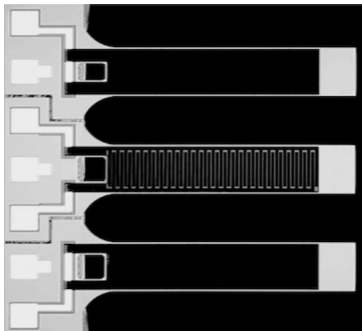


Image courtesy of Joan Pons-Nin et al.

Energy harvesting & timing, implantable hearing aids, atomic force microscopy, optics and photonics, and real time health monitoring.

Pad oxide: 0.2 μm

Piezoelectric film: 0.5 μm

Pad metal: 1.02 μm

Silicon: 10 μm

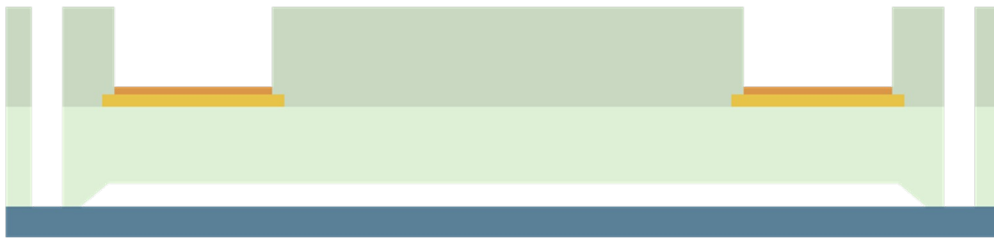
Substrate: 400 μm

Buried oxide: 1 μm

- Five masks
- SOI wafer
- Distinct metal and piezoelectric (AlN) layers

Thin Film Electronics (TFE)

As needed, ~6 week cycle time



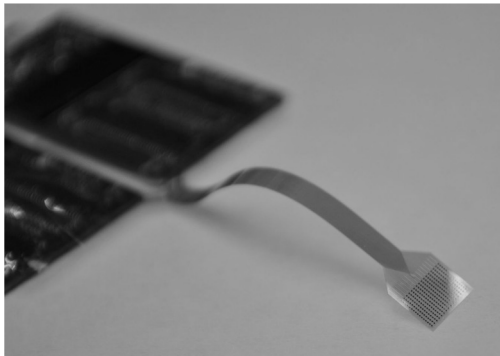
Polyimide 1: 5 μm

Metal 1: 0.24 μm

Polyimide 2: 5 μm

Top metal: 0.10 μm

- Three masks
- Two polyimide layers
- Two metal layers

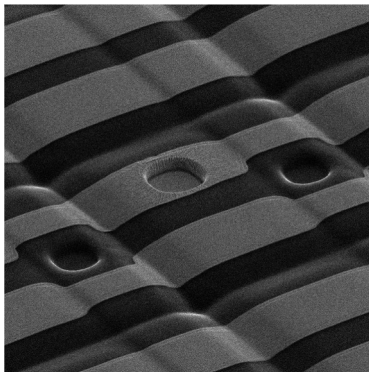
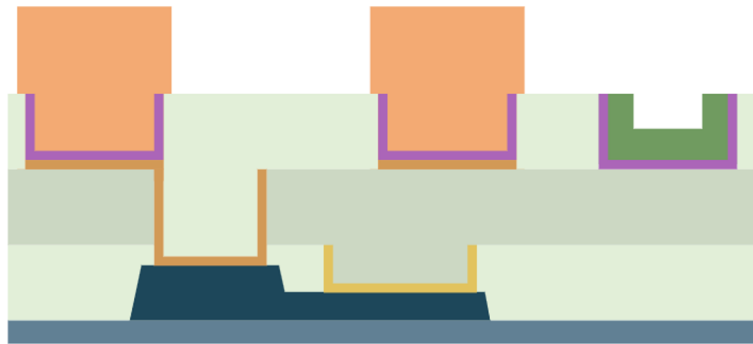


internal 256ch μECoG array

Flex cables, interposers, neural interface devices (NIDs)

2 Layer TFE + μ LEDs

As needed, ~8-12 week cycle time



Additions to TFE

- Multi-layer routing
- MicroLEDs
- Electroplating
- New electrode materials

Plating: 17 μ m

TiN 0.5 μ m

Top Metal: 0.12 μ m

Polyimide 3: 2.5 μ m

Metal 2: 0.26 μ m

Polyimide 2: 2.5 μ m

Metal 1: 0.26 μ m

Polyimide 1: 5 μ m

GaN LED: 5.5 μ m

- 8-11 masks
- Three polyimide layers
- Three metal layers
- Electroplating
- GaN uLEDs

Public process documentation & design guidelines

Docs - Science

science.xyz/docs/mems-soi/index

Science Docs

Overview
Process overview
Design rules
Design standards
Changelog

Documentation / MEMS / Silicon-on-Insulator Standard Technology

Silicon-on-Insulator Standard Technology

Creating wafers with the SOI MEMS process will result in a chip with up to five layers: pad metal, silicon, substrate, buried oxide, and blanket metal.

	Thickness (µm)	Resistance (Ω/□)
Pad metal	0.52 ± 0.10	0.055 ± 0.010
Silicon	25 ± 1	20 ± 5
Substrate	400 ± 5	N/A
Buried oxide	2.0 ± 0.1	N/A

Docs - Science

science.xyz/docs/mems-piezo/index

Science Docs

Overview
Process overview
Design rules
Design standards
Changelog

Documentation / MEMS / Piezo Standard Technology

Piezo Standard Technology

Creating wafers with the Piezo MEMS process will result in a chip with up to six layers: pad film, pad oxide, silicon, buried oxide, and substrate.

	Thickness (µm)	Resistance (Ω/□)	Resistivity (Ω/□cm)	Purpose
Pad oxide	0.202 ± 0.08	N/A	N/A	This layer isolates the silicon from the piezoelectric film or pad metal layers.
Piezoelectric film	0.5	N/A	N/A	This layer can be used for piezoelectric sensors. The film uses aluminum nitride and has a strain coefficient between 3.4-6.5 (pC/N).
Pad metal	1.02	0.055 ±	N/A	This layer is perfect for precision alignment but is limited to

Docs - Science

science.xyz/docs/mems-poly/index

Science Docs

Overview
Process overview
Design rules
Design standards
Changelog

Documentation / MEMS / Polysilicon Standard Technology

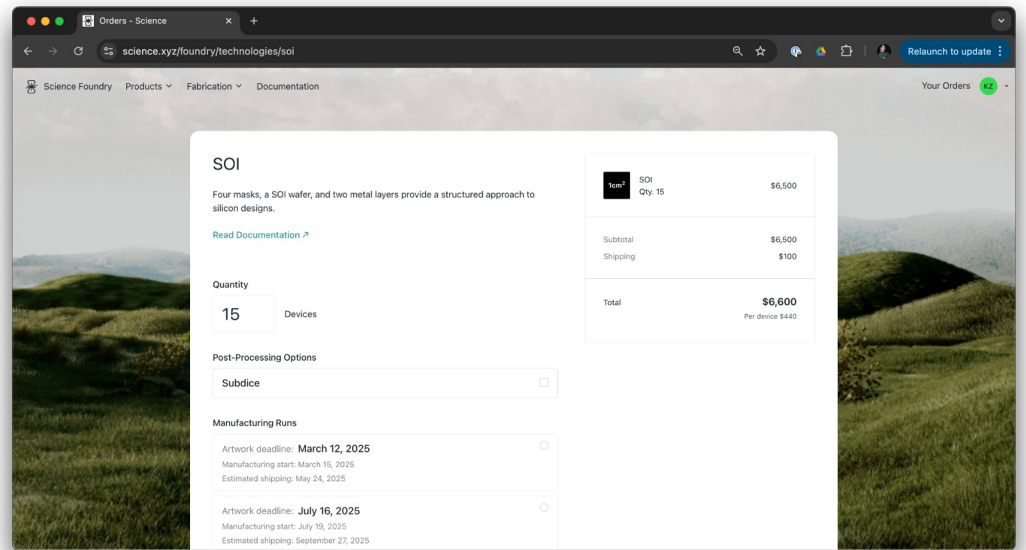
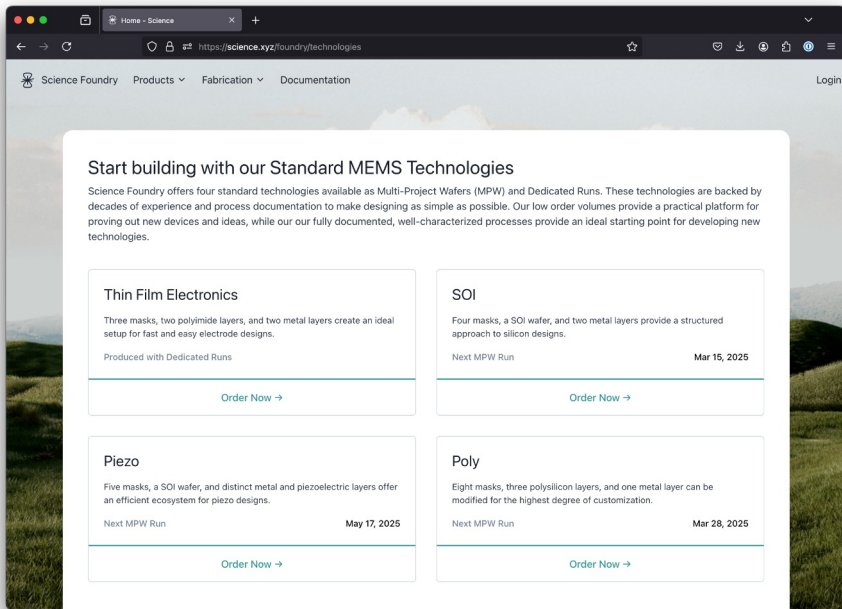
Polysilicon Standard Technology

Creating wafers with the Poly MEMS process will result in a chip with eight layers: nitride, three polysilicon layers, metal, two sacrificial oxide layers, and a substrate.

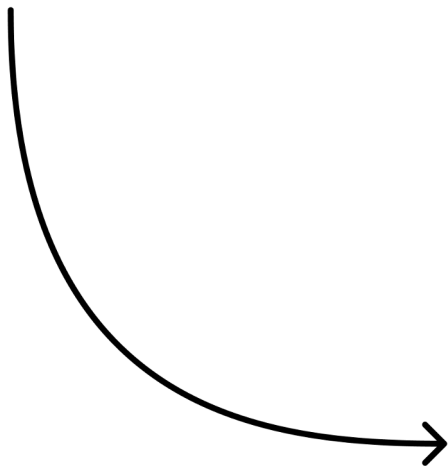
	Thickness (µm)	Resistance (Ω/□)	Residual stress (MPa)	Purpose
Nitride	0.60 ± 0.07	N/A	50 ± 50	This layer insulates the silicon layers from the substrate.
Polysilicon 0	0.5			
Polysilicon 1	2.0			
Oxide 1	0.5			
Polysilicon 2	1.5			
Metal	0.5			
Substrate				

Layer name	Thickness (µm)	Purpose
Metal 1	0.24	This layer is ideal for routing traces and defining electrode sites.
Top metal	0.10	This layer is ideal for remetalizing electrode sites and connection pads.
Polyimide 1	5	This layer forms the base of the device.
Polyimide 2	5	This layer insulates the routing traces.

Examples



Adding additional Standard Technologies requires extensive process development...



Needed to figure out an efficient way to do this without sacrificing production timelines

Custom Manufacturing Execution System (MES)

Inventory

Items

Equipment

Locations

Bill of Materials

Search...

Total Inventory Items

207

ITEM NAME

BrainPhys™ Neuronal Medium

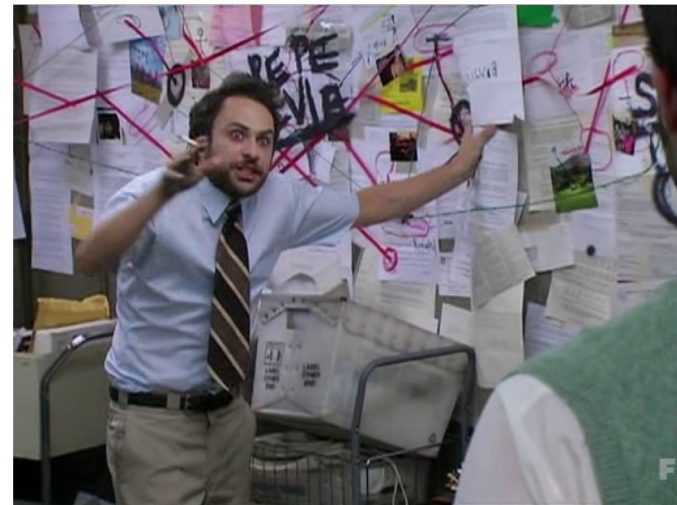
DMEM with 4500 mg/L D-Glucose

CloneR2

A standard MEMS Fab is already a complex beast

High-Mix Manufacturing

- Wide variety of products
- Mixed Volumes
- Frequent Process Adjustments
- High Degree of Customization



Throw in R&D and it only gets worse!

Science Foundry's Solution: Model the entire fab in software

- Protocols
- Jobs
- People
- Tools
- Shifts
- Raw Materials
- Deadlines

Multi-Step Workflows

The screenshot displays the Foundry software interface for editing a workflow titled "Axon Probe LED Shortloop". The interface includes a search bar, navigation tabs for Workflows, Jobs, Tools, and Documents, and a user profile icon. Below the title, there are buttons for "Exit Edit Mode", "Discard Changes", and "Save".

<input type="checkbox"/>	LEVEL	PROTOCOL	PE NOTES
<input type="checkbox"/>	1 L1	Lot Start Procedure →	• GaN Epi Wafers • Scribe backs
<input type="checkbox"/>	2 L10	SC1 - 80C, 20min →	Assuming we want sc1 instead of pir since not outsourcing
<input type="checkbox"/>	3 L10	Pr 3: 3.45µm SC 1827 Coat with Liquid Prime, BEBR and SB →	Send 5/10 through this photo for mesa etch characterization. Will use etch rate to inform next 5 through deep etch
<input type="checkbox"/>	4 L10	PE05 General Exposure →	Use chuck 1 for thick wafers
<input type="checkbox"/>	5 L10	Wafer 6 Inch Develop →	
<input type="checkbox"/>	6 L10	LED01 General Process →	mesa etch
<input type="checkbox"/>	7 L10	LED01 Luminosity Review →	review luminosity
<input type="checkbox"/>	8 L10	PE Traveler Review →	review subsequent steps to see if resist will hold up to deeper etch with etch rate/ selectivity info from first 5 wafers
<input type="checkbox"/>	9 L20	WH03 Solvent General Process →	

At the bottom of the interface, there are buttons for "+ New Step (CTRL + SPACE)" and "Import Steps".

Select and insert protocols and sequences of protocols

Tight integration with inventory and procurement systems

The screenshot displays a Foundry management interface. At the top, the Foundry logo is on the left, and a search bar and navigation menu (Workflows, Jobs, Tools, Documents) are on the right. Below the logo, there is a 'Back to Jobs' link and the job title 'Job 742' with a 'Queued' status. A 'Filter' button, '+ Add Wafer' button, and 'Pause Job' button are also visible.

The main content area is divided into two sections. On the left, there is a sidebar with 'Steps' (Finance, Wafers) and a detailed view for Job 742. The 'Wafers' section is highlighted. The job details include:

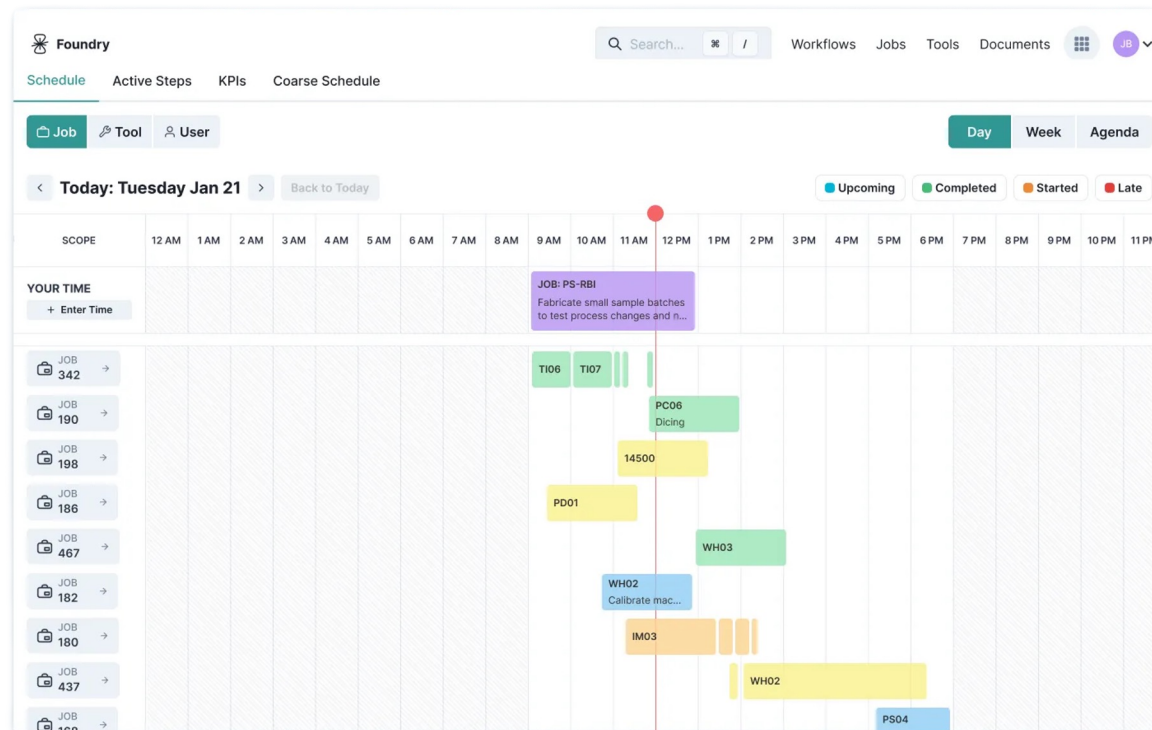
- ID: 742
- WORKFLOW: Axon Probe LED Sho...
- DATE STARTED: Dec 1, 2024
- DEADLINE: Aug 15, 2025
- EST TOTAL DAYS: 257
- LAST MODIFIED: Jan 19, 2025, 8:38 AM
- ASSIGNEE: Jodi Brown

At the bottom of the sidebar, there is an 'Abort Job' button. The right section is a table listing 10 wafers:

ID	WAFER TYPE	DATE CREATED	SERIAL #	STATUS
190-001	150mm, 440, 2, 40, DSP, 150	Dec 1, 2024 04:48 AM	2503-001-01	Good
190-002	150mm, 440, 2, 40, DSP, 150	Dec 1, 2024 04:48 AM	2503-001-01	Good
190-003	150mm, 440, 2, 40, DSP, 150	Dec 1, 2024 04:48 AM	2503-001-03	Good
190-004	150mm, 440, 2, 40, DSP, 150	Dec 1, 2024 04:48 AM	2503-001-04	Good
190-005	150mm, 440, 2, 40, DSP, 150	Dec 1, 2024 04:48 AM	2503-001-05	Good
190-006	150mm, 440, 2, 40, DSP, 150	Dec 1, 2024 04:48 AM	2503-001-06	Good
190-007	150mm, 440, 2, 40, DSP, 150	Dec 1, 2024 04:48 AM	2503-001-07	Good
190-008	150mm, 440, 2, 40, DSP, 150	Dec 1, 2024 04:48 AM	2503-001-08	Good
190-009	150mm, 440, 2, 40, DSP, 150	Dec 1, 2024 04:48 AM	2503-001-09	Good
190-010	150mm, 440, 2, 40, DSP, 150	Dec 1, 2024 04:48 AM	2503-001-10	Good

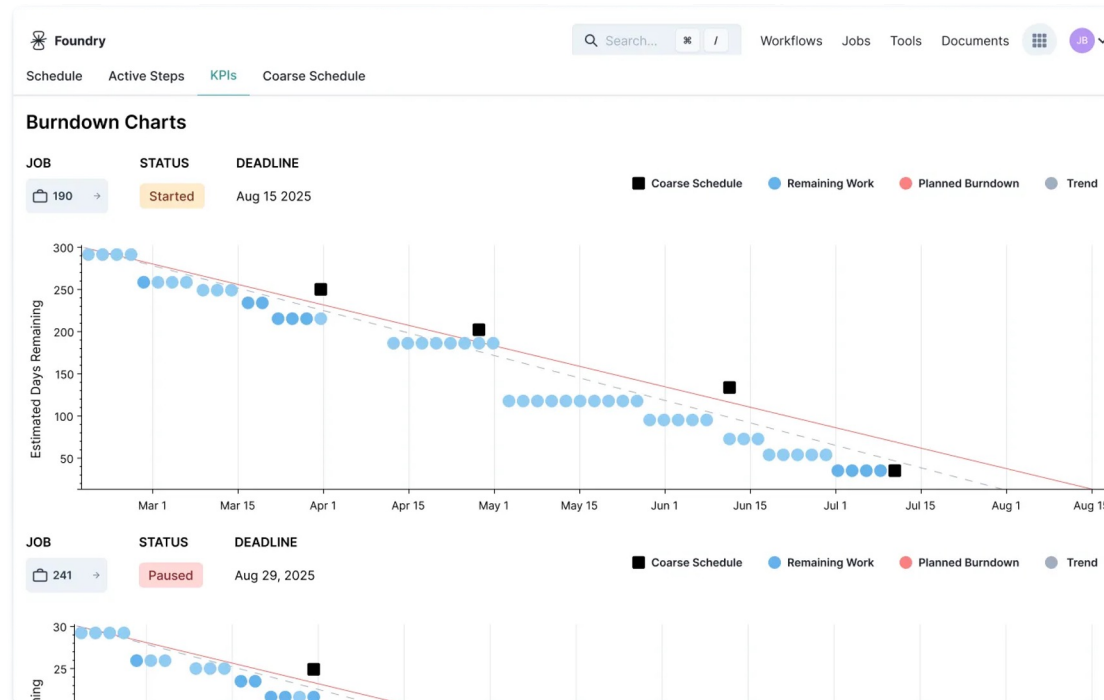
Manage inventory levels through to shipping finished products

Timeline-based schedule for each day



Scheduling algorithm optimizes for productivity and predictability

Burndown charts



Monitor job adherence to expected schedule and adjust accordingly

What does this mean for our customers?

Software has enabled a more versatile Foundry

- Science Foundry is a commercial foundry that specializes in smaller volume, early-stage development
- Our streamlined interface for planning and developing new processes captures all of the information required while also providing flexibility during the development process



Early Stage Development	Production Process Development	Volume Production
<ul style="list-style-type: none">● Prove out a design● Smaller wafer lots● Development support	<ul style="list-style-type: none">● Robust and repeatable production process development● Multiple development lots	<ul style="list-style-type: none">● Process validation● Produce wafers in volume● 10s to 1000s wafers per year

Bridging the gap from development to production



Universities - R&D Facilities

- Shared tools
- Unstable processes
- Non-production environment
- Once proof of concept/prototype developed, still costly transfer to commercial foundry

Science Foundry

- Commercial foundry with production tools
- R&D capacity to support development
- Allows for smaller development runs
- Development support
- Quick turn on development
- Supports volume production from 10s to 1000s wafers

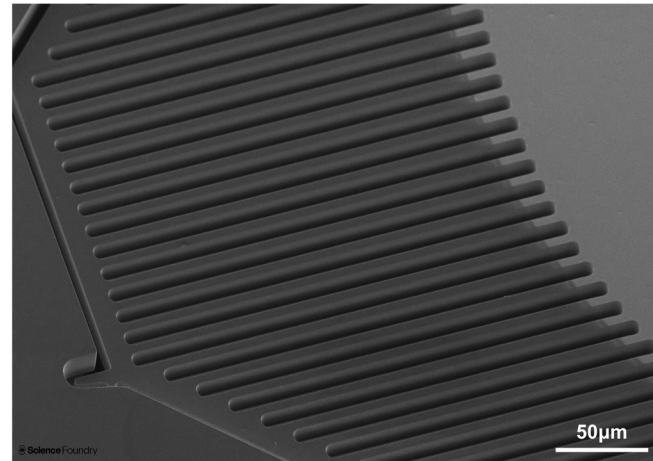
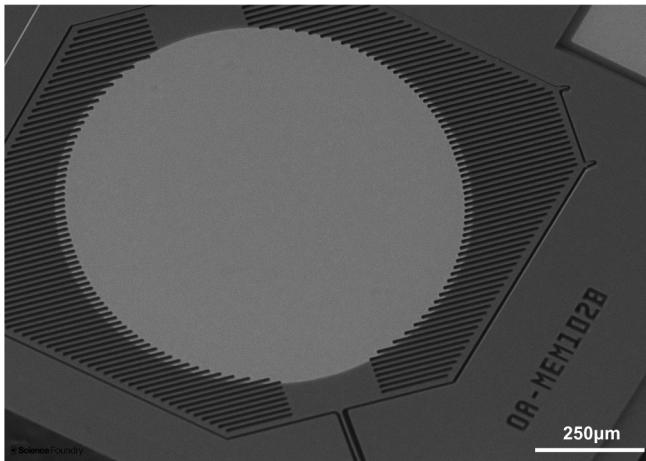


Typical Commercial Foundry

- Large minimum spend required
- Want proven design and process flow
- Limited R&D capacity
- Longer time for development

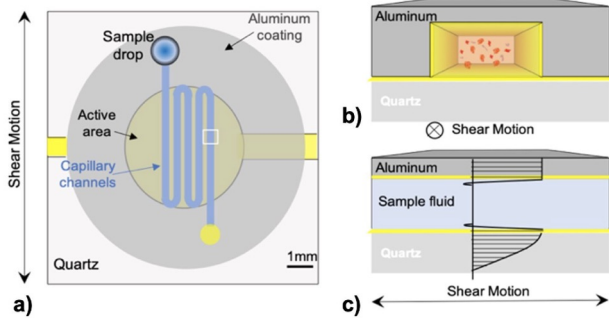
Variable Optical Attenuators - MEMSCAP

Volume Production

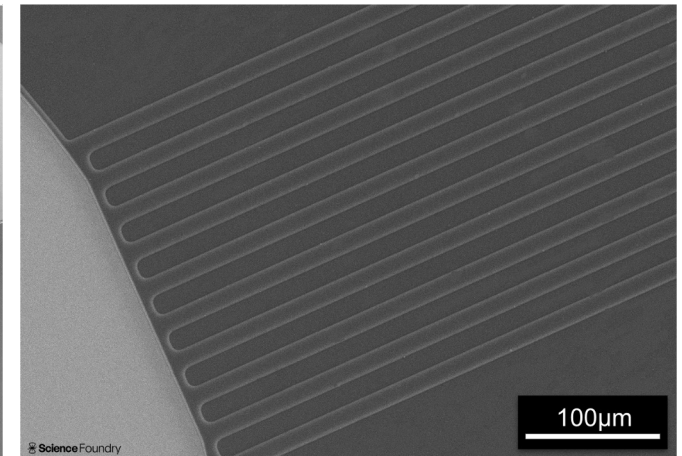
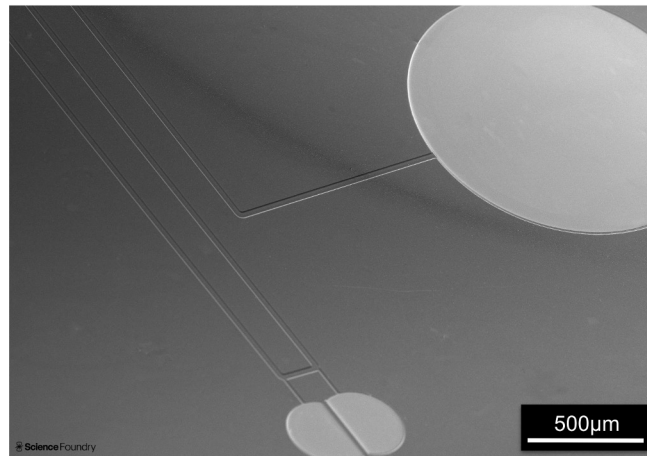


Microfluidics - Qatch Technologies

Late-stage development/ Pre-production

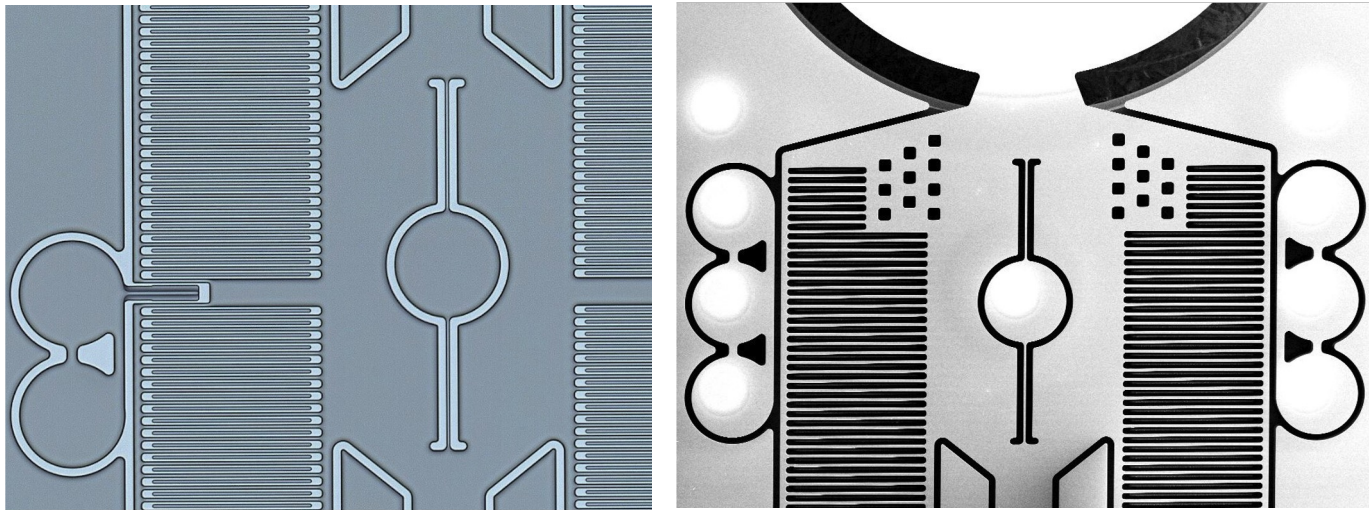


a) Top view, **b)** side view, looking into a single microfluidic channel with fluid, **c)** side view of a channel with shear motion indicated. (drawings not-to-scale in this depiction)



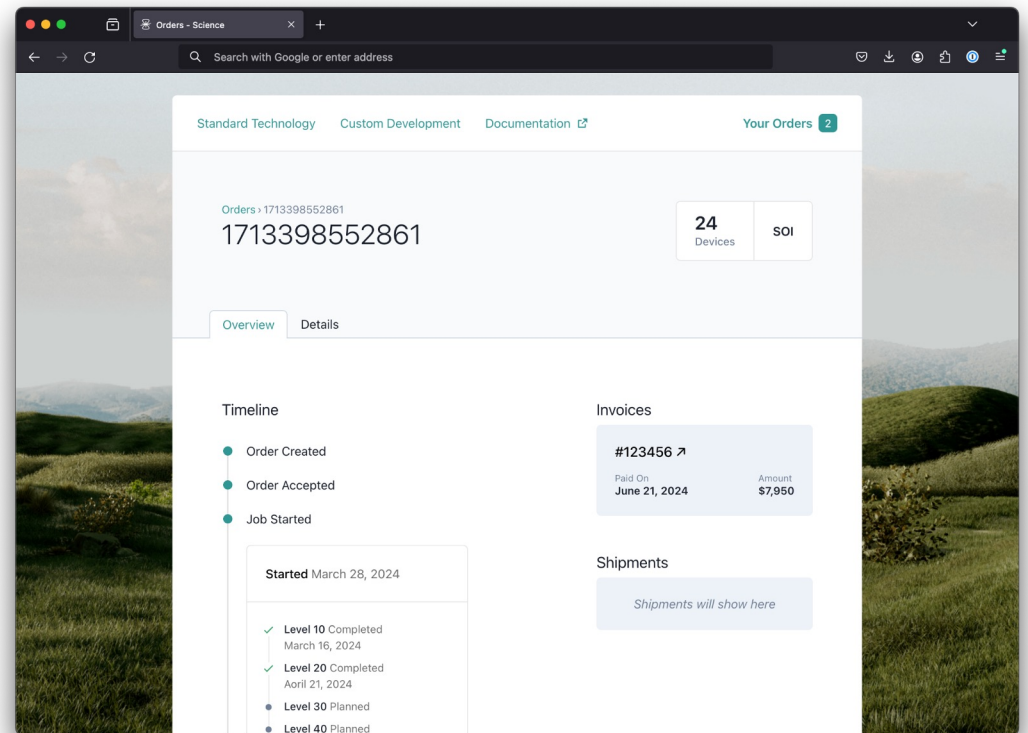
μ Mirrors for LiDAR - Omnitron Sensors

Early feasibility



At every stage, we provide transparency & predictability to customers.

Data-driven, tightly aligned partnerships to accelerate time-to-market for MEMS devices.





TRDU 870477 8

25GB

2.9m
9'6"

CXWL

Modular Fab Expansion

Modular infrastructure has many advantages

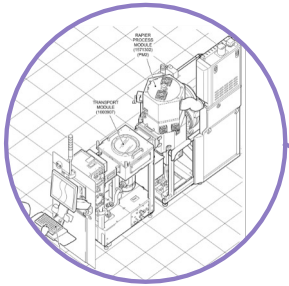
- Goes up quickly
- Simplifies design
- Allows for phased movement
- Rinse & repeat

Nondescript location

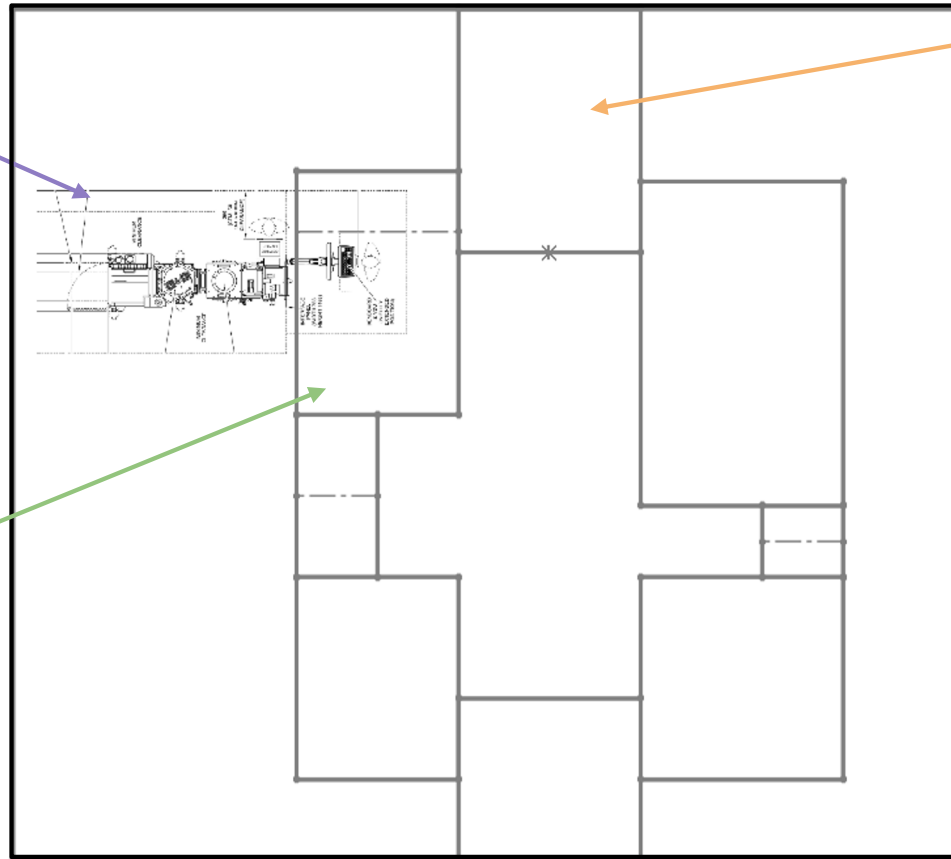


There are 10s of thousands of distribution warehouses throughout the US

Configurable base unit



Tools



Softwall Gown Room & Hallway

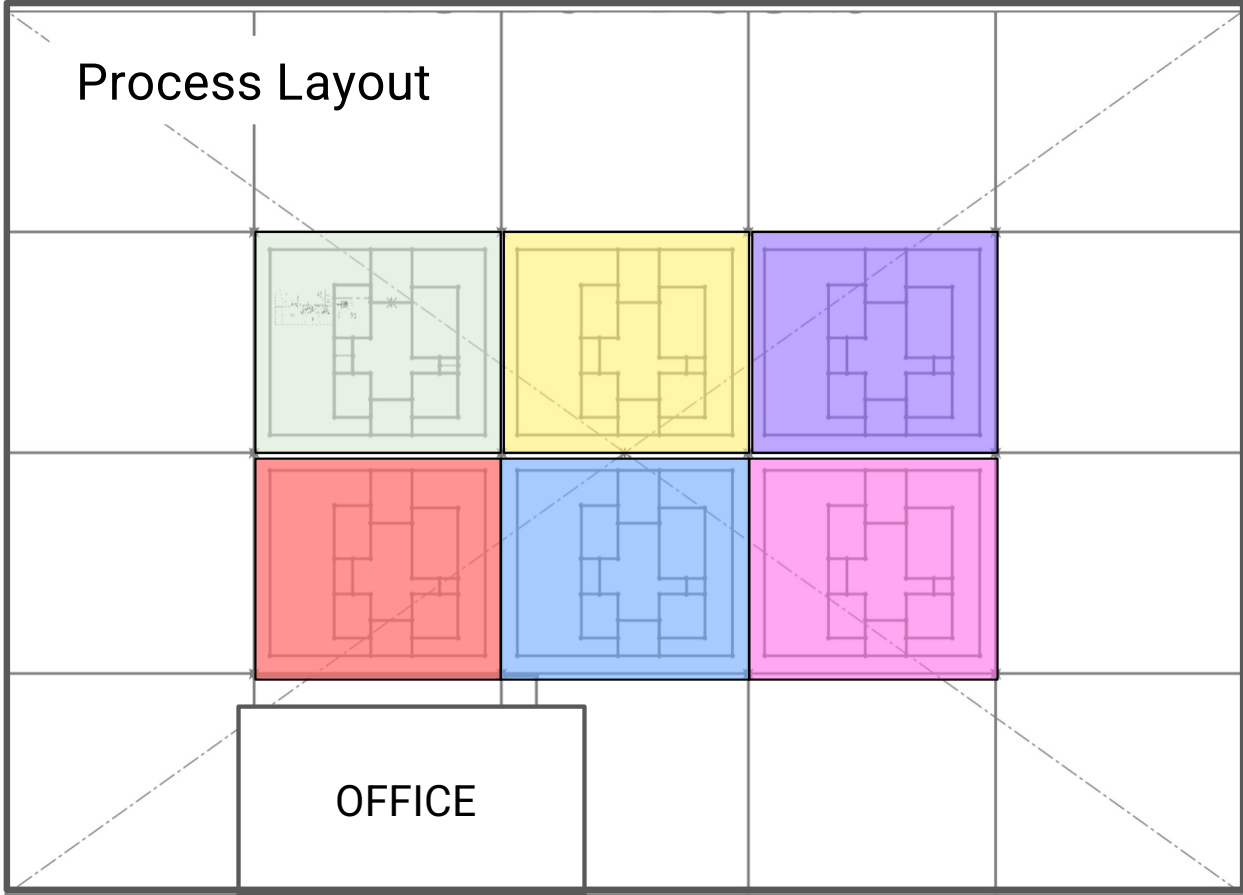


Softwall Cleanroom



Steel Insulated Barn (Chase)

Separate modules by process capability



- 1 = Non-Toxic Dry Etch
- 2 = Photolithography
- 3 = Wafer Level Testing
- 4 = Toxic Dry Etch & PECVD
- 5 = Diffusion & LPCVD
- 6 = Wet Chemistry



First module operational this month!



Thinking about infrastructure differently allows for flexibility and agility

- Science will continue to vertically integrate and leverage internal needs for the benefit of our customers
- Developing a “kit of parts” for rapid execution of more manufacturing space allows us to remain nimble in times of uncertainty

The MEMS foundry business has innovation.

EXPENSIVE

INEFFICIENT

SLOW

CONVOLUTED

OUTDATED

The MEMS foundry business has innovation.

**SCIENCE
FOUNDRY**

EXPENSIVE INEFFICIENT
LOW CONVOLUTED
UPDATING

Thank you!
science.xyz/sws



Kara Zappitelli
Foundry Director
karaz@science.xyz



Scott Smyser
VP of Sales
scotts@science.xyz
+1-818-259-2785